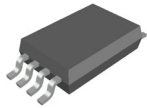
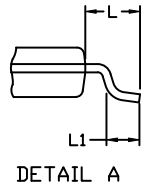
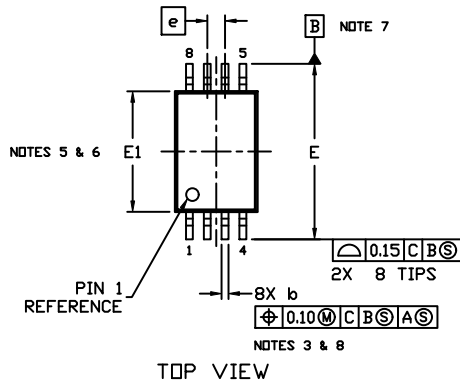


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



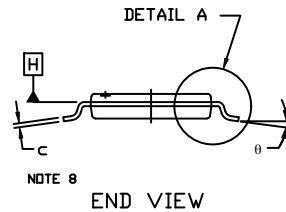
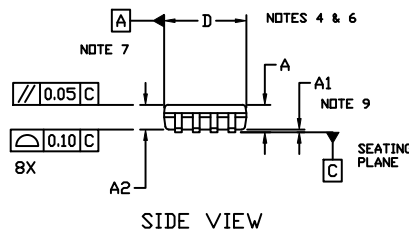
TSSOP8, 4.4x3.0, 0.65P
CASE 948AL
ISSUE A

DATE 20 MAY 2022



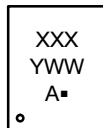
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5, 2009..
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL NOT BE 0.15 IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION *D* DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
5. DIMENSION *E1* DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS *D* AND *E1* ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM PLANE *H*.
7. DATUMS *A* AND *B* ARE TO BE DETERMINED AT DATUM *H*.
8. DIMENSIONS *b* AND *c* APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP..
9. *A1* IS DEFINED AS THE LOWEST VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY..



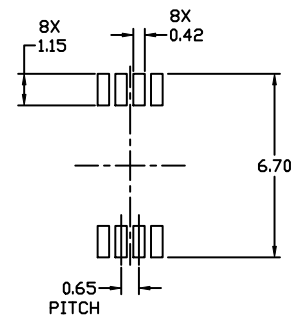
| DIM | MILLIMETERS | | |
|----------|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | --- | --- | 1.20 |
| A1 | 0.05 | --- | 0.15 |
| A2 | 0.80 | 0.90 | 1.05 |
| <i>b</i> | 0.19 | --- | 0.30 |
| <i>c</i> | 0.09 | --- | 0.20 |
| D | 2.90 | 3.00 | 3.10 |
| E | 6.30 | 6.40 | 6.50 |
| E1 | 4.30 | 4.40 | 4.50 |
| <i>e</i> | 0.65 BSC | | |
| L | 1.00 REF | | |
| L1 | 0.50 | 0.60 | 0.70 |
| θ | 0° | --- | 8° |

GENERIC
MARKING DIAGRAM*



- XXX = Specific Device Code
- Y = Year
- WW = Work Week
- A = Assembly Location
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|------------------|------------------------|--|
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| DESCRIPTION: | TSSOP8, 4.4X3.0, 0.65P | PAGE 1 OF 1 |

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